

# Novo™ Series: Model 102

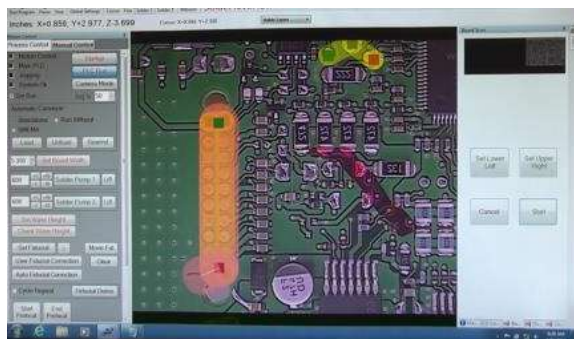
## Selective Soldering Platform with Compact Footprint and Outstanding Value

### Features and Benefits

- Selective soldering of printed circuit boards as large as 406 x 406 mm (16.0 x 16.0 in.)
- Standalone platform ideal for prototype, cell manufacturing or batch production requirements
- Interchangeable solder pots and pumps compatible with tin-lead, lead-free and HMP solder alloys
- Choice of single selective solder nozzle, dual selective nozzles with independent control or 75 mm wide wave soldering nozzle
- SWAK-OS graphics-based programming and machine control software enables fast and straightforward program creation

The Novo™ 102 is a robust selective soldering platform delivering an exceptional combination of versatility, productivity and value. The Novo™ 102 has many unique features, including high speed Z-axis motion for faster processing time and reduced soldering cycle.

**Flexibility.** With its feature rich, graphics-based programming and machine control software, the Novo™ 102 is specially designed for demanding selective soldering applications. Set-up and time to first article is significantly reduced to within 10-15 minutes. The SWAK-OS software features seamless fiducial recognition, live teach cameras, real time data collection, SQL backend data extraction and complete FIS capability for shop floor integration.



SWAK-OS graphics-based programming software



**Soldering Technology.** With its flexible configuration, the Novo™ 102 is a versatile selective soldering platform capable of processing tin-lead, lead-free or HMP solder alloys. Interchangeable solder pots and pumps are available with either single selective solder nozzle, dual selective nozzles with independent control or 75 mm (3.0 in.) wide wave soldering nozzle. The nitrogen inerted dual nozzle system enables the use of multiple size nozzles within the same program further enhancing flexibility and productivity.

**Process Control.** Nordson SELECT's optional closed-loop rotary encoders and other advanced process control capabilities have been incorporated into the Novo™ 102, enhancing solder quality, precision and yield capabilities.

**Value.** With a reputation for innovation, comprehensive process solutions from Nordson SELECT ensure a maximum return on investment and low cost of ownership. From initial process development through full-scale production, you are supported by our experienced worldwide engineering, applications development and technical service network.

## Novo™ 102 Features

The Novo™ 102 is a fully configured selective soldering platform and is a reliable and cost-effective solution for many demanding through-hole and SMT mixed-technology soldering applications including:

- Printed circuit board assemblies and other solderable substrates
- Interchangeable tin-lead and lead-free soldering

**Choice of soldering nozzles** - single selective nozzle, dual selective nozzles or 75 mm wave nozzle



Single solder nozzle    Dual solder nozzles    75 mm wave nozzle



Standard atomizing spray flux applicator and available FluxJet precision drop-jet dispenser

**Interchangeable solder pots** and pumps for tin-lead, lead-free and HMP solder alloys

**Single monitor** and available dual monitors for simultaneous viewing of all process functions

**SWAK-OS** graphics-based programming and machine control software



Seamlessly creates true-to-scale image of entire board    Paint flux and solder paths to create and edit programs

**Standalone platform** with universal PCB location rails and motor driven adjustment

### Standard Features

Universal PCB location rails with motor driven adjustment and multiple board stops for processing several boards at one time  
High speed Z-axis motion  
Atomizing spray flux applicator  
Tin-lead solder pot and pump assembly with 6 mm and 12 mm quick change magnetically coupled bullet nozzles  
Automatic solder pot level monitoring and fill system  
Automatic wave height monitoring and adjust system  
Solder alloy verification system  
Heated nitrogen inerting system  
Programming and fiducial alignment look-up camera  
Process witness camera  
SWAK-OS graphics-based programming and machine control software

- Automatic fiducial alignment
- Board warp compensation
- On-board help videos
- Remote machine diagnostics
- Complete FIS capability

Single monitor

### Optional Features

Universal PCB location fixture  
FluxJet precision drop-jet dispenser  
In-process flux verification system for drop-jet  
Dual flux heads, 2 atomizing spray heads, 2 drop-jet flux dispensers or one of each  
Topside infrared preheater with closed-loop control  
Dual process witness cameras  
Automatic solder nozzle tinning system  
Lead-free solder pot and pump assembly (titanium)  
HMP solder pot and pump assembly  
Dual nozzle solder pot and pump assembly, tin-lead or lead-free (titanium)  
3-25 mm bullet nozzles or 4-25 mm mini-wave nozzles  
75 mm (3.0 in.) wide wave nozzle and pump assembly, tin-lead or lead-free (titanium)  
Solder pot exchange cart with warming controls  
Closed-loop rotary encoders  
Bottom-side nitrogen spot preheater  
Nitrogen de-bridging knife  
Off-line programming software  
Dual monitors  
Six channel thermal data logging system  
Barcode reader

# Specifications: Novo™ 102

## Motion System

Z accuracy	±50 µm (0.002 in.)
Z repeatability <sup>(1)</sup> :	±50 µm (0.002 in.), 3 sigma
Z velocity:	0.15 m/s peak (6 in./s)
X-Y accuracy	±50 µm (0.002 in.)
X-Y repeatability <sup>(1)</sup> :	±50 µm (0.002 in.), 3 sigma
X-Y velocity:	0.2 m/s peak (8 in./s)

## Computer

PC with Windows® operating system

## Software

SWAK-OS graphics-based programming and machine control software

## Solder Pot Capacity and Weight

Capacity <sup>(2)</sup>: Approx. 13.6 kg (30.0 lbs.)  
Total weight of tin-lead solder together with solder pot and pump assembly <sup>(2)</sup>: Approx. 24.0 kg (53.0 lbs.)  
Total weight of lead-free solder together with solder pot and pump assembly <sup>(2)</sup>: Approx. 21.3 kg (47.0 lbs.)

## Solderable Area (X-Y)

Single bullet, dual bullet or mini-wave nozzles <sup>(3,4)</sup>:  
Max. 406 x 406 mm (16.0 x 16.0 in.)  
Min. 50 x 50 mm (2.0 x 2.0 in.)

## Board Handling Capability

Max. board size: 406 x 406 mm (16.0 x 16.0 in.)  
Min. board size: 50 x 50 mm (2.0 x 2.0 in.)

## Board Clearance

Max. overboard clearance: 102 mm (4.0 in.)  
Max. underboard clearance: 102 mm (4.0 in.)

## Facilities Requirements

System footprint:	1194 x 1411 mm (47.0 x 55.5 in.)
Air supply:	Less than 10 CFH @ 90-100 psi
Power (mains) <sup>(5)</sup> :	Power supply accommodates 120VAC, 60 Hz, 15 A standard or 208/220-240VAC, 60 Hz single phase, 15 A optional 30 A with topside preheating <sup>(6)</sup>
Nitrogen <sup>(7)</sup> :	99.999% pure @ 60-100 psi, 30-60 CFH consumption
Ventilation:	Rear 250 CFM recommended, two 100 mm (4.0 in.) dia. ducts
System weight <sup>(8,9)</sup> :	381 kg (840 lbs.)

- (1) Repeatability is measured at full rated system speed.
- (2) Solder capacity and total weight of solder pot and pump assembly varies depending on solder alloy.
- (3) Substrates as small as 50 x 50 mm (2.0 x 2.0 in.) are possible without the need for fixturing or other tooling.
- (4) Contact factory regarding smaller boards/carriers.
- (5) Electrical power varies depending on configuration.
- (6) Topside preheating only available with 208/220-240VAC, 60 Hz, single phase power supply.
- (7) Nitrogen consumption is solder nozzle dependent and machine configuration dependent.
- (8) System weight varies depending on configuration.
- (9) Configuration dependent. Other configurations may be available. Contact Nordson SELECT.

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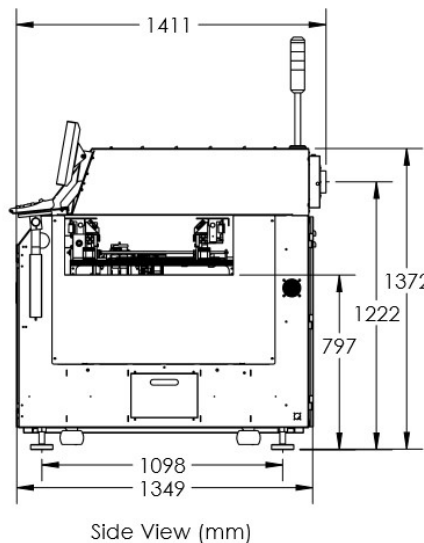
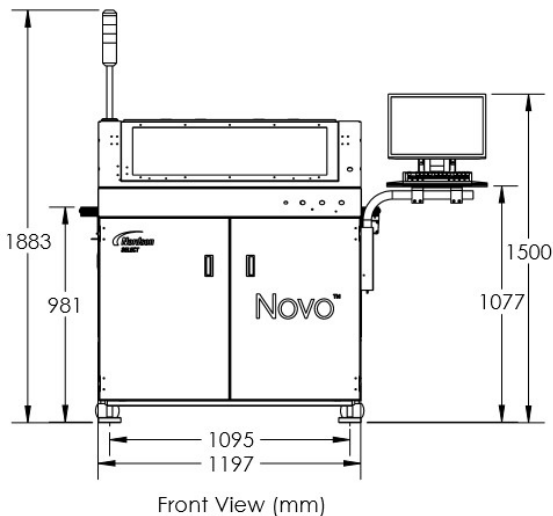
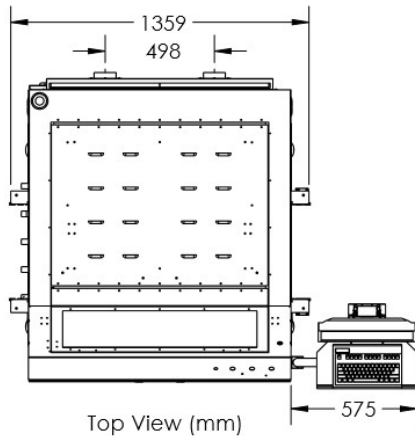
## Standards Compliance

SMEMA

**Additional options may be available: contact Nordson SELECT for further information.**

# Novo™ 102

Dimensions are in millimeters



**For more information, speak  
with your local representative  
or contact your regional office.**

**[Nordsonselect.com](http://Nordsonselect.com)**

**North America**

*Headquarters*

Spokane Valley, WA, USA

+1.509.924.4898

[info@nordsonselect.com](mailto:info@nordsonselect.com)

**China**

Email:

[info@nordsonselect.com](mailto:info@nordsonselect.com)

Shanghai

+86.21.3866.9166

Beijing

+86.10. 8453.6388

Guangzhou

+86.20.8554.9996

**Europe**

Maastricht, Netherlands

+31. 43.352.4466

[info@nordsonselect.com](mailto:info@nordsonselect.com)

**Japan**

Tokyo

+81.3.5762.2801

[Info@nordsonselect.com](mailto:Info@nordsonselect.com)

**Korea**

Seoul

+82.31.765.8337

[info@nordsonselect.com](mailto:info@nordsonselect.com)

**India**

Chennai

+91. 44.4353.9024

[info@nordsonselect.com](mailto:info@nordsonselect.com)

**S.E. Asia/Australia**

Singapore

+65.6796.9514

[info@nordsonselect.com](mailto:info@nordsonselect.com)

**Taiwan**

+886.229.02.1860

[info@nordsonselect.com](mailto:info@nordsonselect.com)

**Nordson SELECT, Inc.**

**+1.509.924.4898 Phone**

**[sales.usa@nordsonselect.com](mailto:sales.usa@nordsonselect.com) Email**

**3010 North First Street**

**Spokane Valley, WA USA 99216-5085**

**[www.nordsonselect.com](http://www.nordsonselect.com)**

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